

Meeting the needs of the SMT Aae



Hot plates HT series

These are easy-to-use high-precision hot plates developed for pre-heated or reflow soldering of SMT PC boards, and can be used in QFP, BGA repair work etc. Model HT-1420 is hot plate designed especially for rework. Model HT-1350 also has (Model HT-1350C) with the cover.

Specifications			
Model	HT-1800	HT-1420	HT-1350
Hot plates	100×100×15mm (2plates)	3types(exchangeable) 50×50×20mm 26×32×20mm 26×26×20mm	120×140×8mm
Operable temperature range	0 to 400°C		0 to 300°C
Temperature precision	±1%		
Sensor	Thermoelectric couple K(CA)		
Temperature control	PID		
Heater	Cartridge heater (300W/120V×2)/plate	Cartridge heater 250W/120V×2	Plate heater 350W
Start-up time (20°C→200°C)	8 minutes	1 minute	7 minutes
Applicable circuit boards	Max 100×100mm	Max 200×200mm	Max 120×140mm
Work plate	180×180mm	-	120×140mm
Power supply	AC100V/120V/220V/240V		
	850W/100V, 1.2kW/120V	360W/100V, 510W/120V	360W
External dimensions	(W)430×(D)180×(H)113mm	(W)200×(D)220×(H)270mm	(W)250×(D)180×(H)116mm
Weight	5kg	2.8kg	2.5kg
Features	 2-stage heating, such as preheating and reflow heating, is possible due to the two independent hot plates. Equipped with a work plate. 	 Exclusive rework hot plate for SMT PC boards. Equipped with a point marker, which makes working with even large boards simple. 	 Equipped with a work plate. Handling work such as reflow soldering after heating is safe and simple.
Applications	 Pre-heat and reflow soldering of Hybrid IC boards and mini-SMT boards. Thermosetting of adhesives. High-precision temperature testing. 	 Rework of SMT PC boards. Removal of QFP of PLCC. Remounting of QFP of PLCC. Partial heating of boards. 	 Pre-heat and reflow soldering of Hybrid IC boards and mini-SMT boards. Thermosetting of adhesives. Other pre-heating or heating work.

* Specifications subject to change without notice.

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